



## **Multimedia Available: Applied Materials' Breakthrough 300mm Copper Electroplating System Drives Interconnect Technology Beyond the 90nm Barrier**

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--(BUSINESS WIRE)--

Applied Materials, Inc. introduces its 300mm SlimCell(TM) electrochemical plating (ECP) system that overcomes the limitations of existing plating technology to deliver a cost-effective, production-worthy tool for current generation manufacturing and groundbreaking capability for 65nm and beyond copper chip development. Key to the SlimCell system is its unique individual-cell chemistry that enables multi-step ECP processing while setting benchmarks in gapfill and defect performance, and cost of ownership.

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